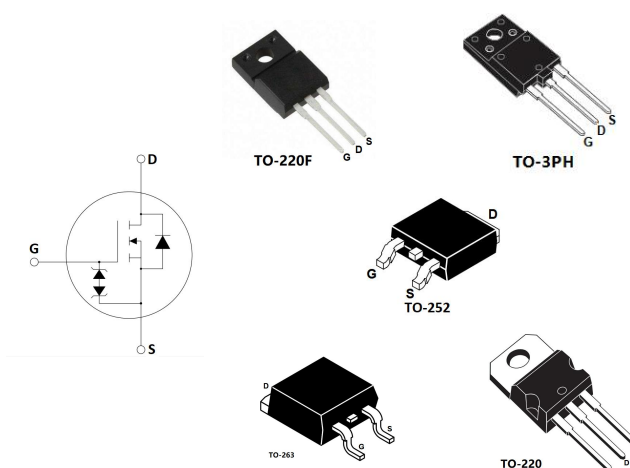


Features

- Extremely high dv/dt capability
- 100% avalanche tested
- Gate charge minimized
- Very low intrinsic capacitances
- Very good manufacturing repeatability



Applications

- Switching application

Electrical ratings(Absolute maximum ratings)

Parameter	Symbol	Value				Unit
		TO-3PH	TO-220F	TO-252	TO-220/ TO-263	
Drain-source voltage (V _{GS} =0)	V _{DS}	1000				V
Transient Gate-source voltage	V _{GSM}	±30				
Continuous Gate-source voltage	V _{GSS}	±20				
Avalanche current repetitive or not-repetitive (pulse width limited by T _j Max)	I _{AR}	5				A
Single pulse avalanche energy (starting T _j =25℃ I _d =I _{AR} V _{dd} =50V)	E _{AS}	583				mJ
Drain current (continuous) at TC=25℃	I _D	5				A
Drain current (continuous) at TC=100℃	I _D	3				
Drain current (pulsed)	I _{DM}	18	18	18	18	
Total dissipation at TC=25℃	P _D	74	48	104	198	W
Operating junction temperature	T _J	-55 to 150				℃
Storage temperature	T _{STG}					
Maximum lead temperature for soldering purpose	T _L	300				℃

Electrical Characteristics($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
On/off states						
Drain-source breakdown voltage	V _{(BR)DSS}	I _D =1mA V _{GS} =0	1000			V
Zero gate voltage drain current (V _{GS} =0)	I _{DSS}	V _{DS} =Max rating			1	μA
		T _C =125°C			50	μA
Gate body leakage current (V _{GS} =0)	I _{GSS}	V _{GS} =±20V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} I _D =250μA	2.0	-	5.0	V
Static drain-source on resistance	R _{DS(on)}	V _{GS} =10V I _D =1A		3.5	4.2	Ω
Forward transconductance	g _{fs}	V _{DS} = 27 V, I _D = 5A		5.6		S
Dynamic						
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Input capacitance	C _{iss}	V _{DS} =25V, f=1MHz, V _{GS} =0		506		pF
Output capacitance	C _{oss}			59		
Reverse transfer capacitance	C _{rss}			3		
Total gate charge	Q _g	V _{DD} =800V, I _D =2.5A V _{GS} =10V, R _G = 4.7 Ω		18.68		nC
Gate-source charge	Q _{gs}			2.1		
Gate-drain charge	Q _{gd}			7.3		
Switching times						
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Turn-on delay time	t _{d(on)}	V _{DD} = 800 V, I _D = 2.5 A, R _G = 25Ω, V _{GS} = 10 V		35.6		ns
Rise time	t _r			22.9		
Turn-off-delay time	t _{d(off)}			42.7		
Fall time	t _f			13.6		
Source Drain Diode						
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Source Drain Current	I _{SD}			5		A
Source Drain Current(Pulsed)	I _{SDM}			18		A
Forward On Voltage	V _{SD}	I _{SD} =5A, V _{GS} =0V		0.8	1.2	V

Reverse Recovery Time	T_{rr}	$I_{SD}=5A$, $di/dt=200A/\mu s$	1.02	μs
Reverse Recovery Charge	Q_{rr}	$V_R=100V, T_j=150^\circ C$	3.68	μC

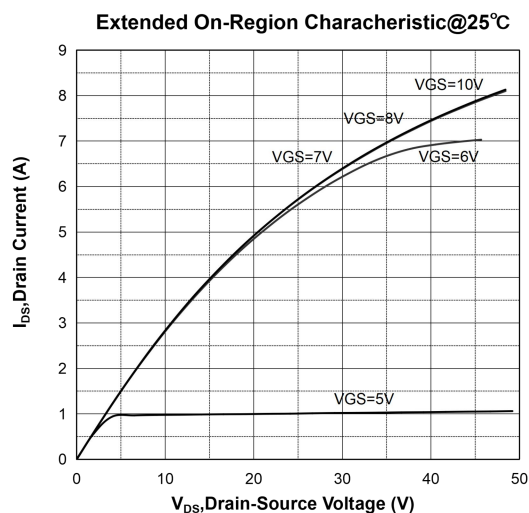
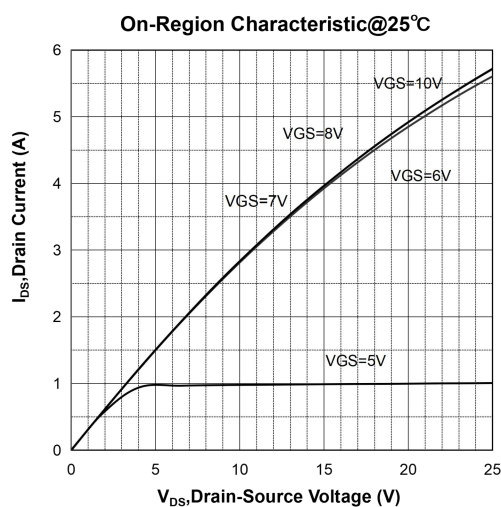
Thermal Characteristics

Parameter	Symbol	Value				Unit
		TO-3PH	TO-220F	TO-252	TO-220/ TO-263	
Thermal resistance junction,max	R_{thj-c}	1.69	2.6	1.2	0.63	$^\circ C/W$
Thermal resistance junction-ambient,max	R_{thc-a}	47.4	58	68	35	$^\circ C/W$

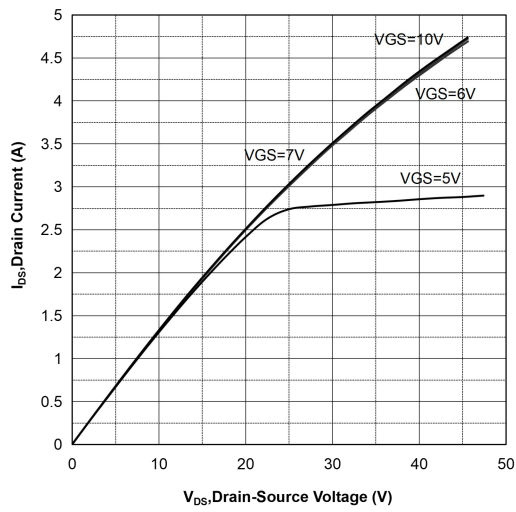
Order codes

Part number	Marking	Package
MS5N100	MS5N100	TO-3PH
MS5N100S	MS5N100S	TO-220F
MS5N100FT	MS5N100FT	TO-220
MS5N100FE	MS5N100FE	TO-263/D2PAK
MS5N100FD	MS5N100FD	TO-252/DPAK

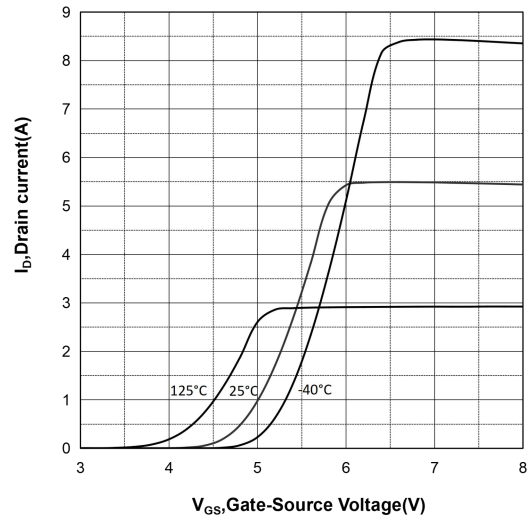
Electrical characteristics (curves)



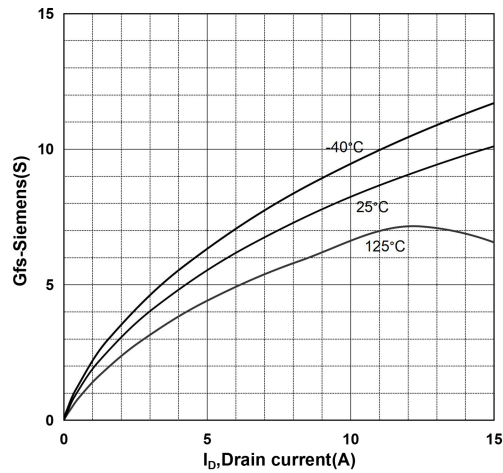
On-Region Characteristic@125°C



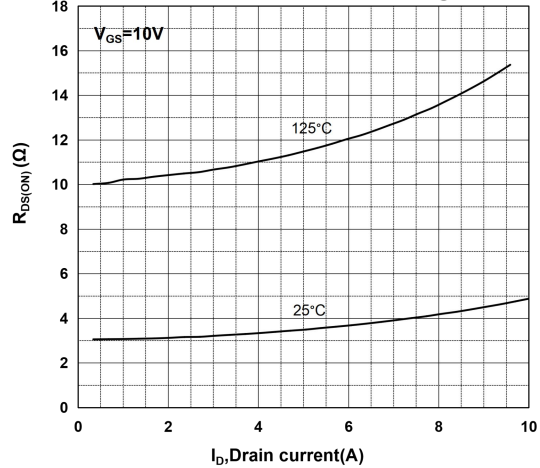
Transfer Characteristics



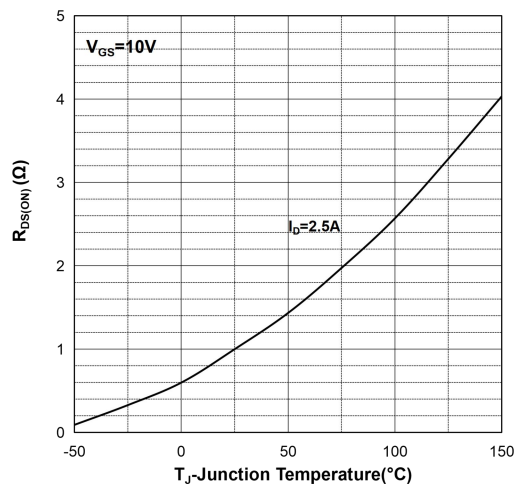
Transconductance



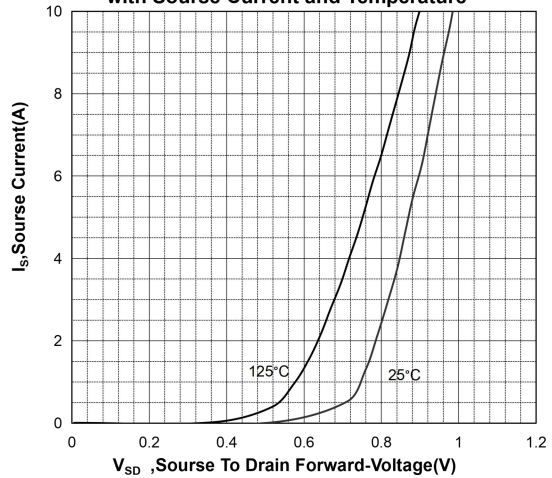
On-Resistance Variation vs Drain Current and Gate Voltage

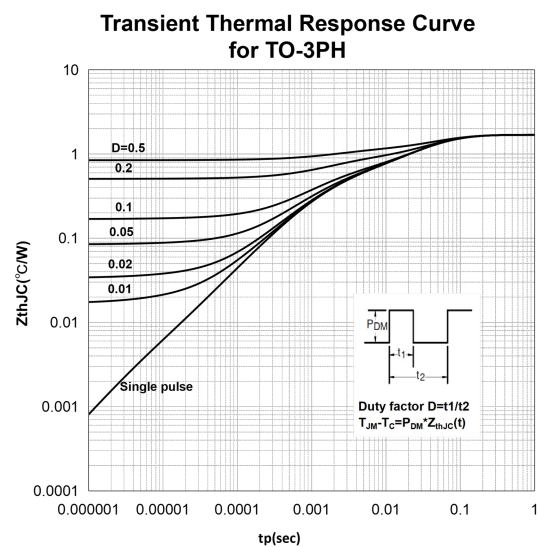
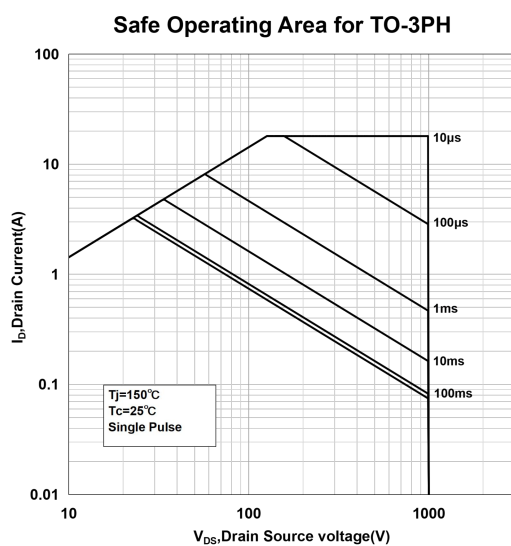
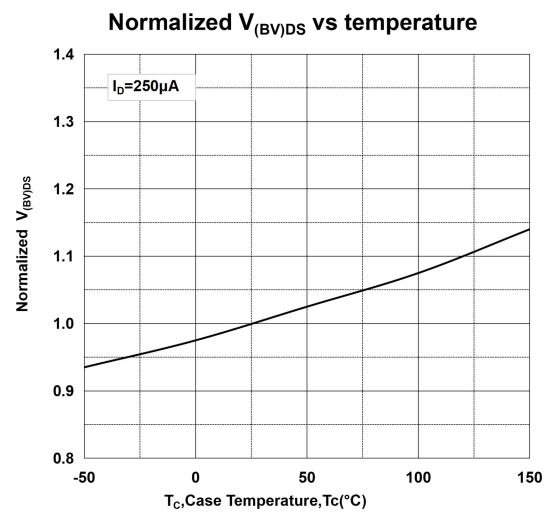
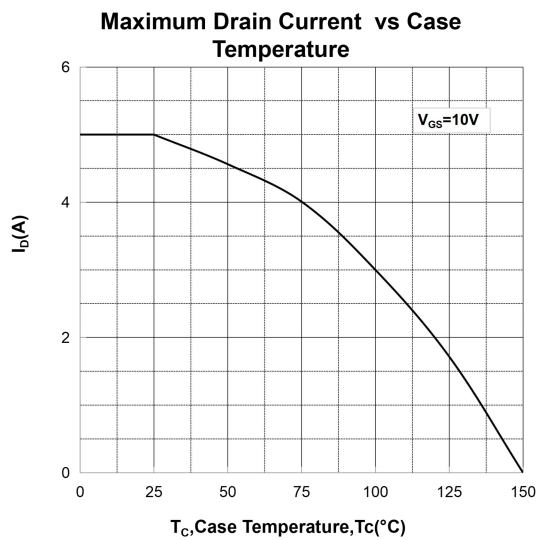
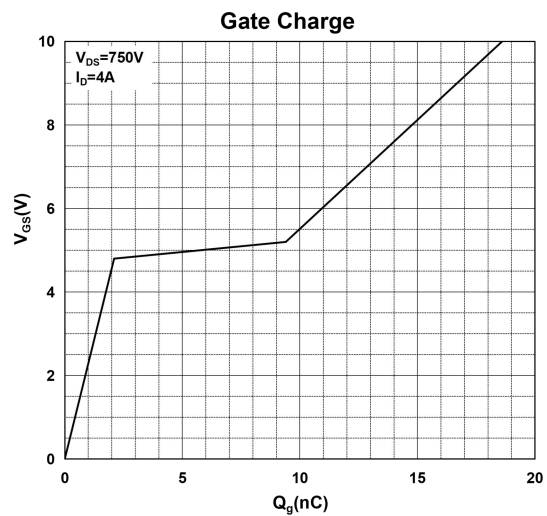
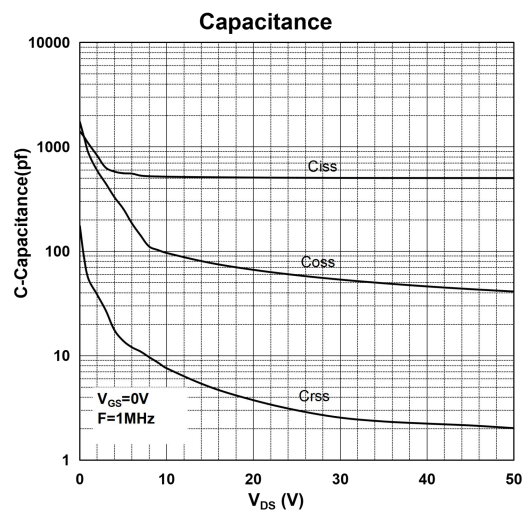


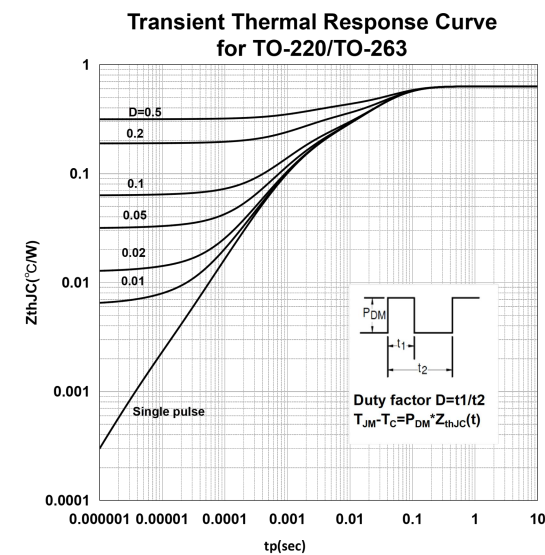
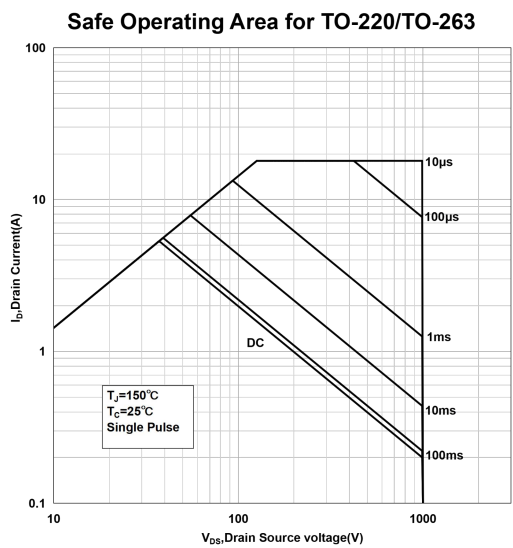
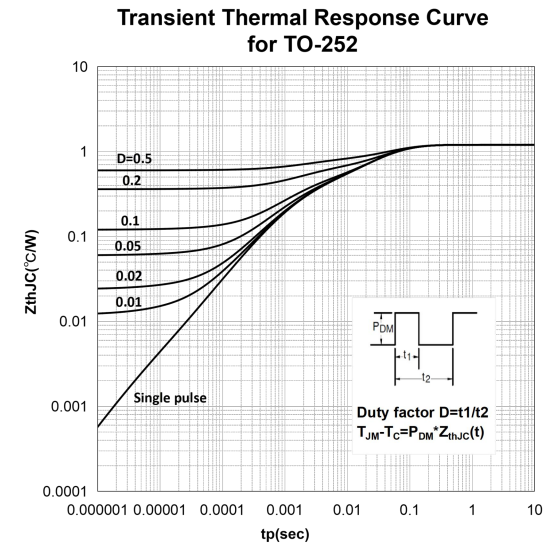
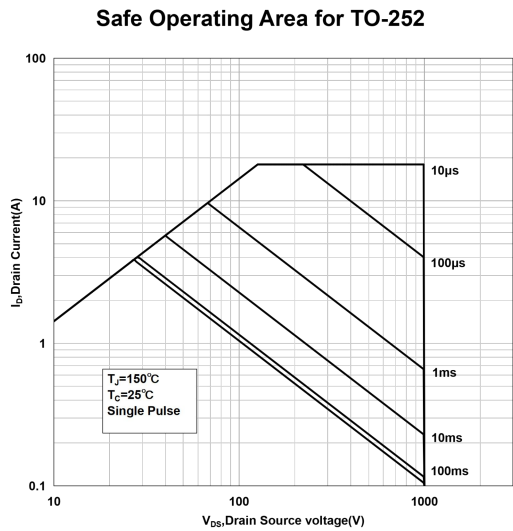
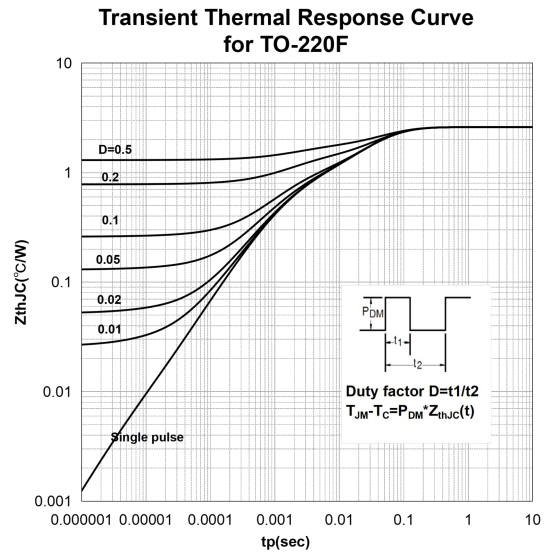
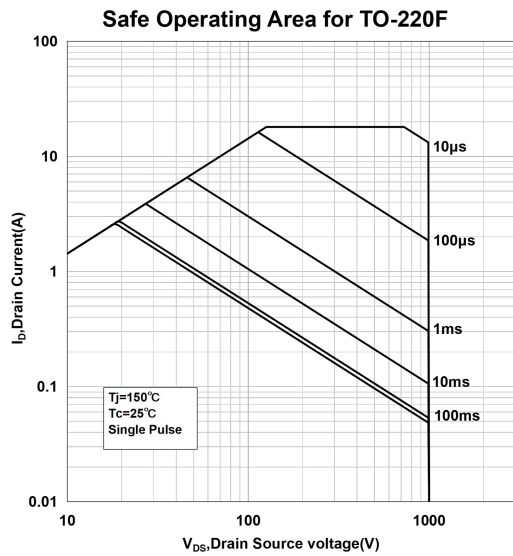
On-Resistance Variation vs Temperature



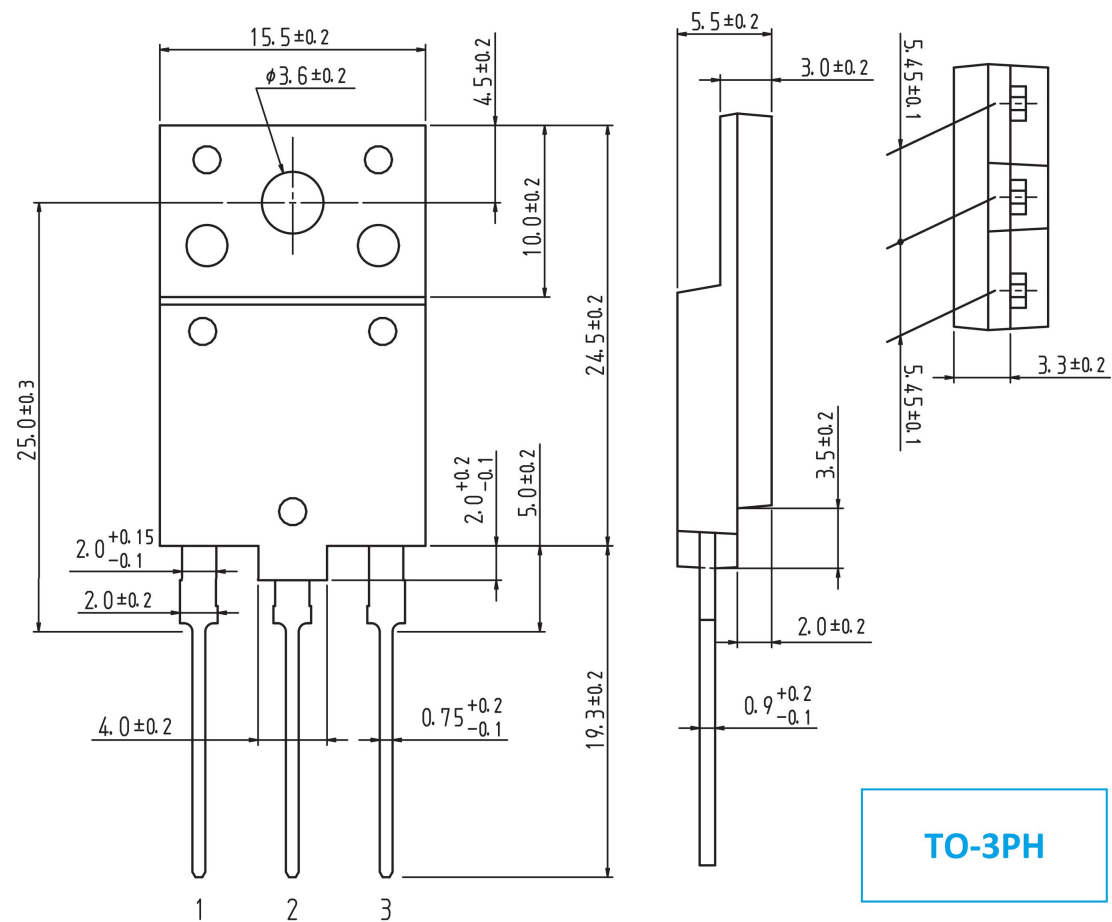
Body Diode Forward Voltage Variation with Source Current and Temperature

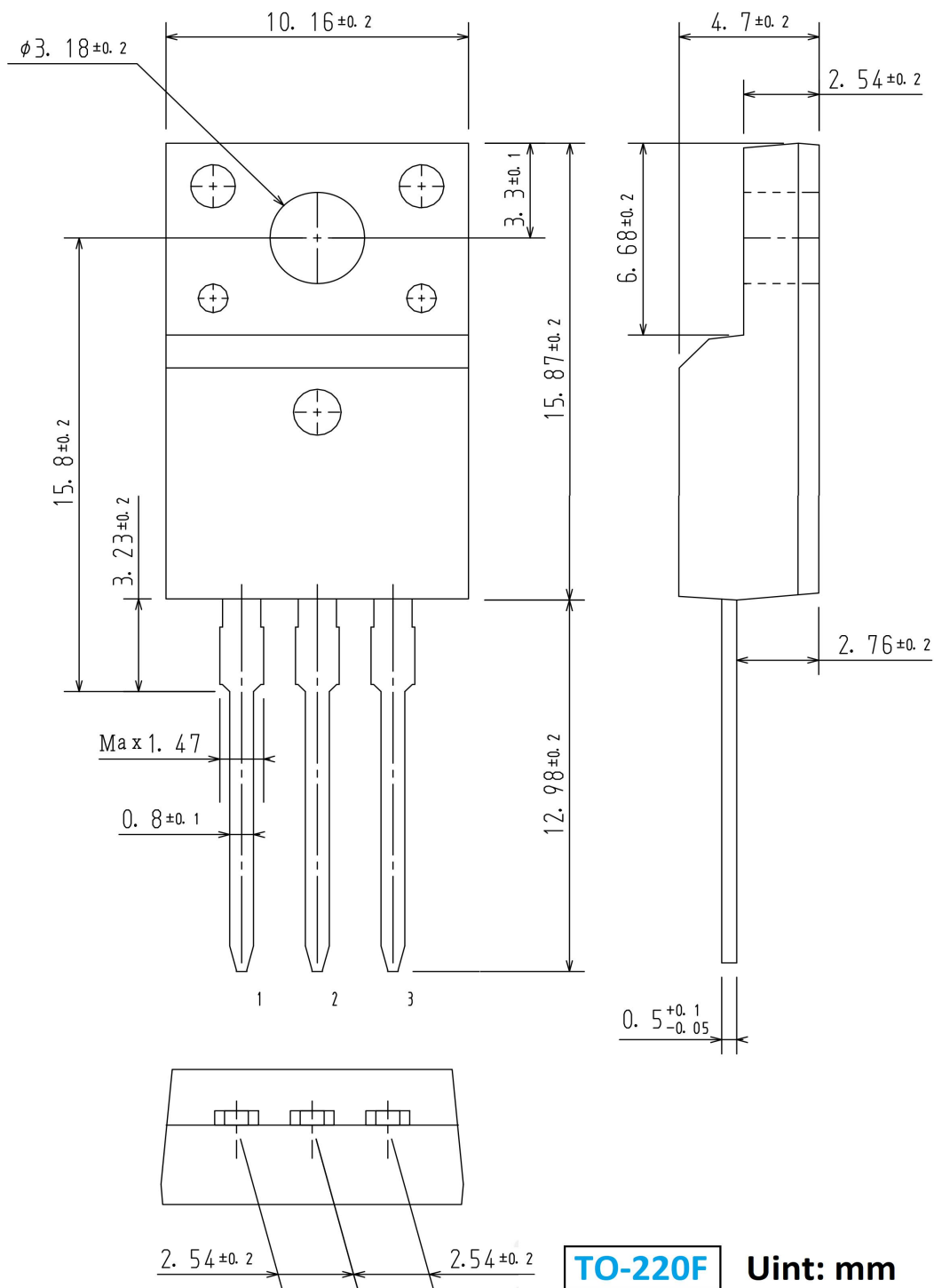


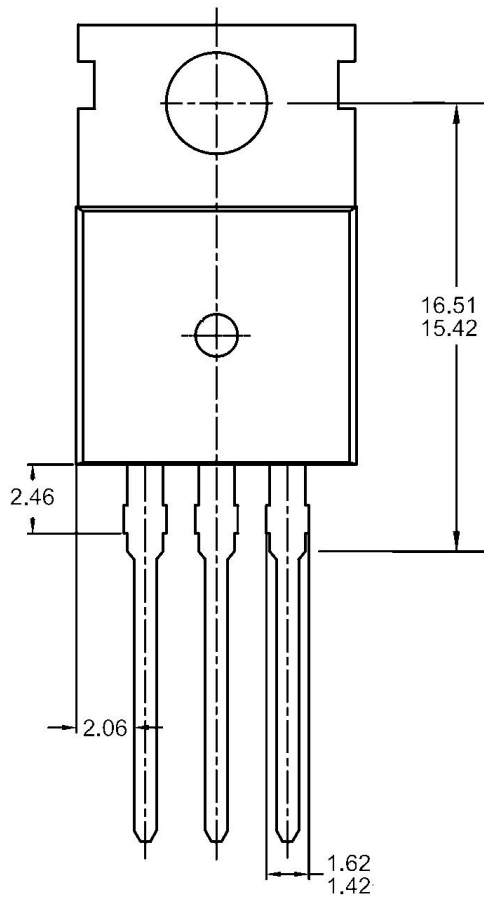




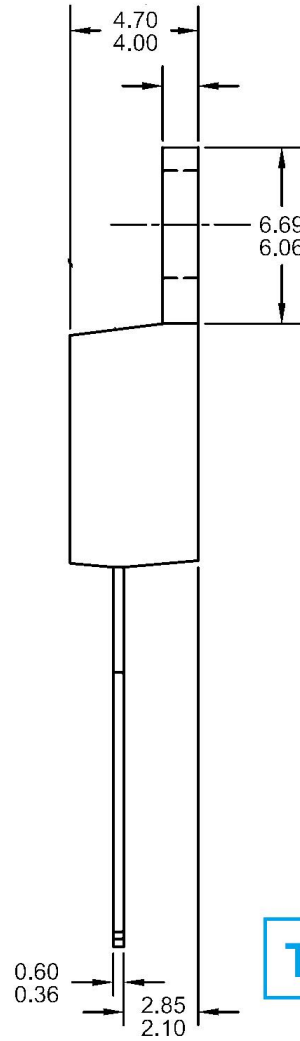
Package outline dimension



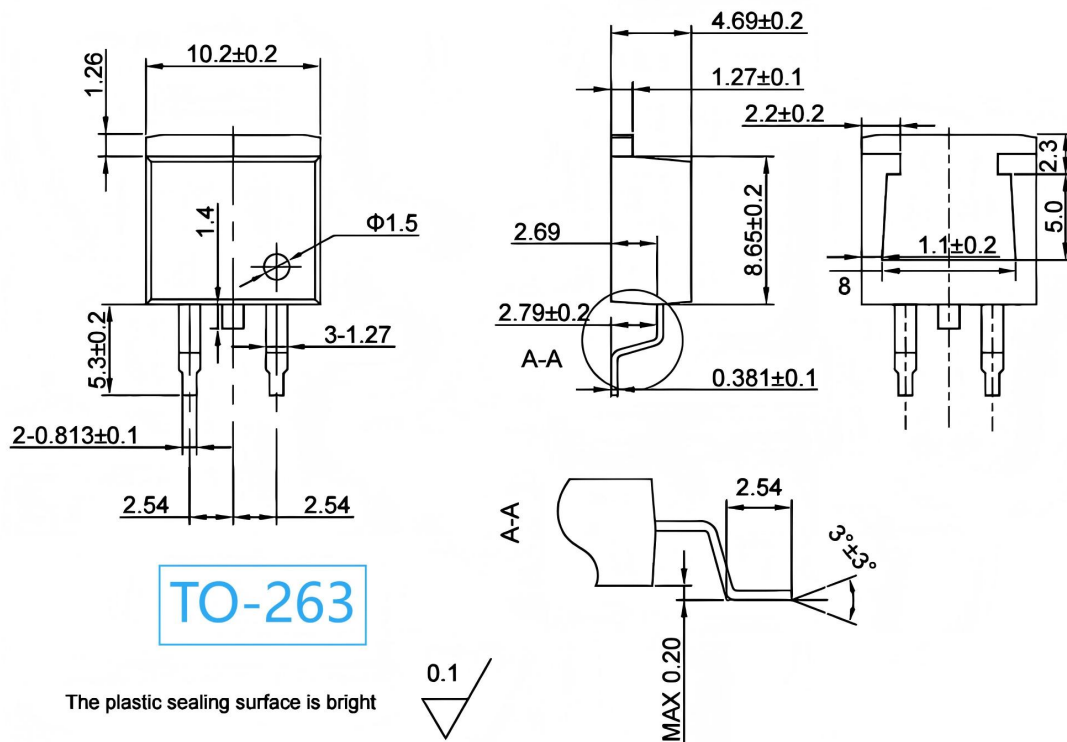




TO-220

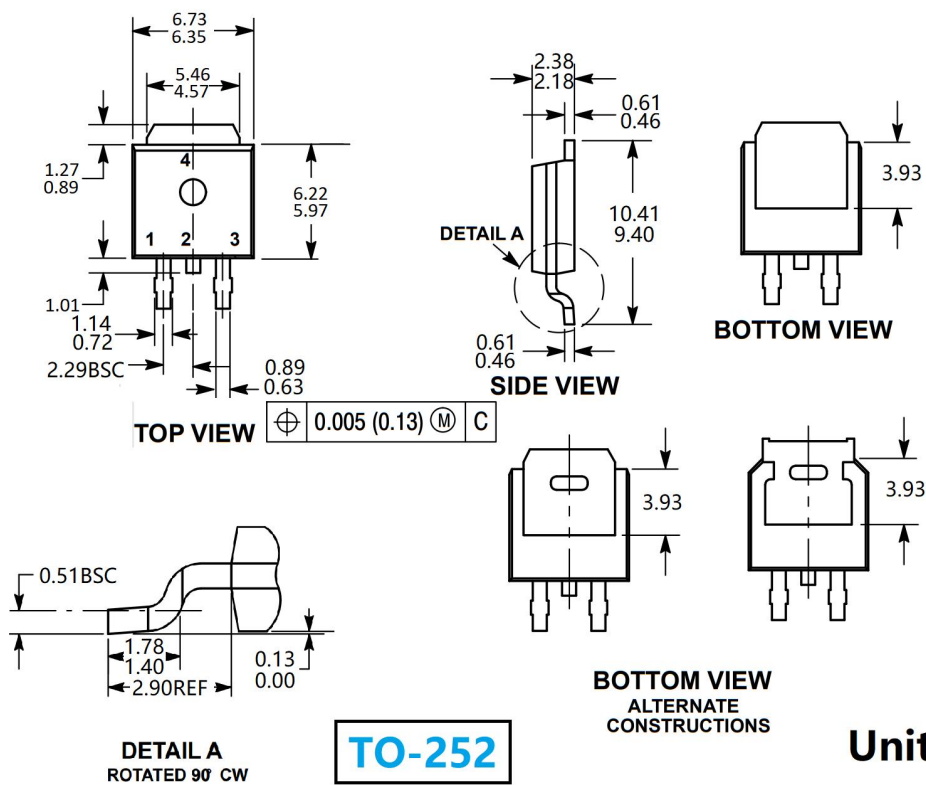


TO-220



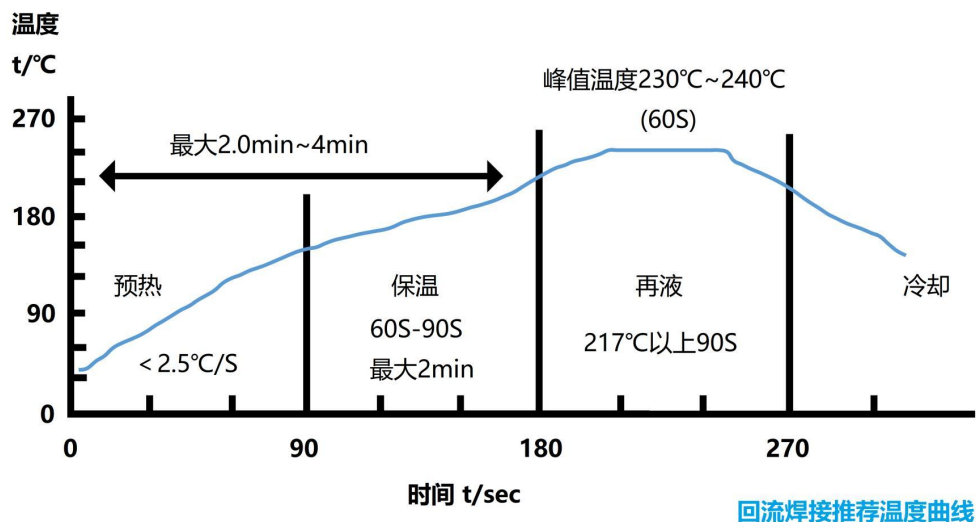
Notes:

1. Unmarked tolerance±0.15mm;unmarked R<0.15mm
2. The resin body is not allowed to have defects, shrinkage holes, cracks, bubbles and other harmful defects
3. The drawing indicates that the leg has reinforcement
4. Unit : mm



Welding temperature curve :

- Reflow Solder temperature curve(MSL 3, SMD)



- Wave soldering temperature curve(Tube)

